



Features

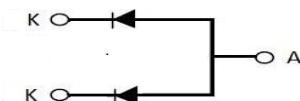
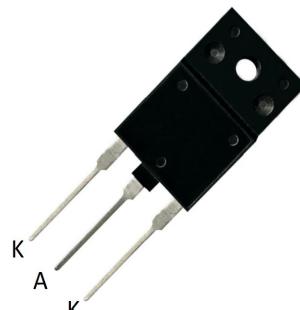
- Adopt FRED chip
- Low forward Voltage drop
- Fast reverse recovery time
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability

Typical Applications

- Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

Mechanical Data

- **Package:** TO-247F-3L
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked



	V_{RSR} V	V_{RRM} V
MUR6060PTR	600	600

■ Maximum Ratings (T_j=25°C Unless otherwise specified)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			600	V
I _{F(RMS)}	RMS forward voltage			60	A
I _{F(AV)}	Average forward current δ = 0.5	T _c = 125°C	Per diode	30	A
		T _c = 110°C	Per device	60	
I _{FSM}	Surge non repetitive forward current	T _c = 100°C	Per diode	40	
		T _c = 80°C	Per device	80	
T _{stg}	Storage temperature range			-65 to + 175	°C
T _j	Maximum operating junction temperature			175	°C

Symbol	Parameter	Value (max.)	Unit
R _{th(j-c)}	Junction to case	Per diode	1.05
		Total	0.68
R _{th(c)}	Coupling	0.3	°C/W

When the diodes 1 and 2 are used simultaneously:
 $\Delta T_j(\text{diode } 1) = P(\text{diode } 1) \times R_{\text{th}(j-c)}(\text{Per diode}) + P(\text{diode } 2) \times R_{\text{th}(c)}$



■Electrical Characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
I_R *	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			25	μA
		$T_j = 150^\circ\text{C}$			80	800	
V_F **	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 30\text{A}$			1.65	V
		$T_j = 150^\circ\text{C}$			1.0	1.25	
		$T_j = 25^\circ\text{C}$	$I_F = 60\text{A}$			1.78	
		$T_j = 150^\circ\text{C}$			1.24	1.55	

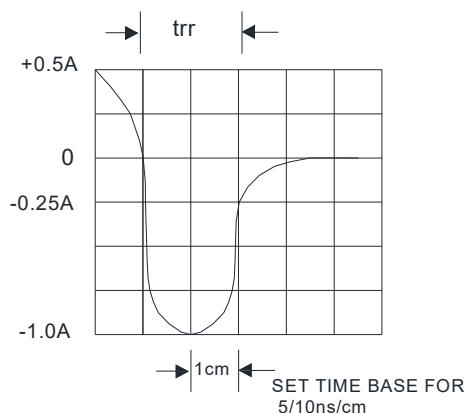
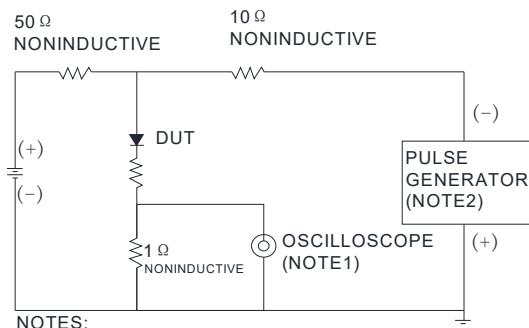
Pulse test: * $t_p = 5 \text{ ms}, \delta < 2\%$

** $t_p = 380 \mu\text{s}, \delta < 2\%$

To evaluate the conduction losses use the following equation: $P = 0.95 \times I_F(\text{AV}) + 0.010 I_F^2(\text{RMS})$

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
t_{rr}	Reverse recovery time	$T_j = 25^\circ\text{C}$	$I_F = 0.5\text{A} \quad I_{rr} = 0.25\text{A} \quad I_R = 1\text{A}$			65	ns
			$I_F = 1\text{A} \quad dI_F/dt = 50 \text{ A}/\mu\text{s} \quad V_R = 30\text{V}$		65	90	
I_{RM}	Reverse recovery current	$T_j = 125^\circ\text{C}$	$I_F = 30\text{A} \quad V_R = 400\text{V}$ $dI_F/dt = 100 \text{ A}/\mu\text{s}$		11.5	16	A
t_{fr}	Forward recovery time	$T_j = 25^\circ\text{C}$	$I_F = 30\text{A} \quad dI_F/dt = 100 \text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$			500	ns
V_{FP}	Forward recovery voltage	$T_j = 25^\circ\text{C}$	$I_F = 30\text{A} \quad dI_F/dt = 100 \text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$		2.5		V

FIG.5: Diagram of circuit and Testing wave form of reverse recovery time





■ Characteristics(Typical)

Figure 1: Conduction losses versus average forward current (per diode)

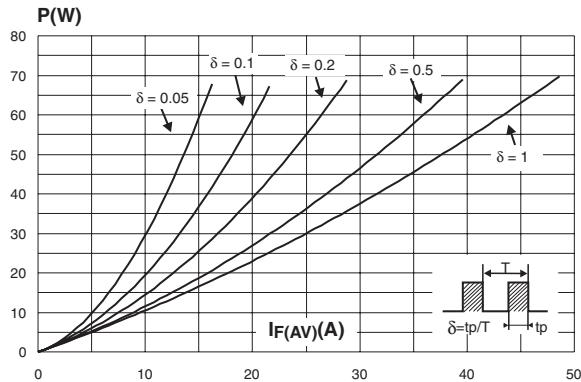


Figure 3: Relative variation of thermal impedance junction to case versus pulse duration

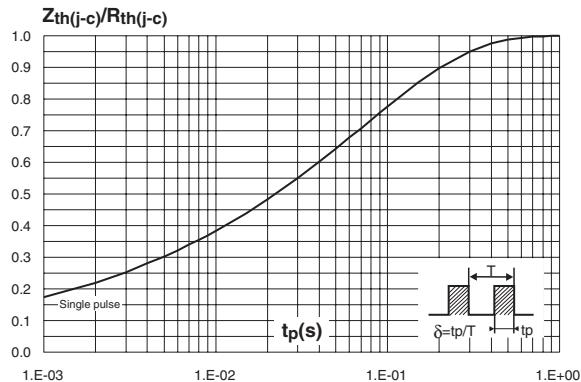


Figure 5: Reverse recovery time versus dI_F/dt (typical values, per diode)

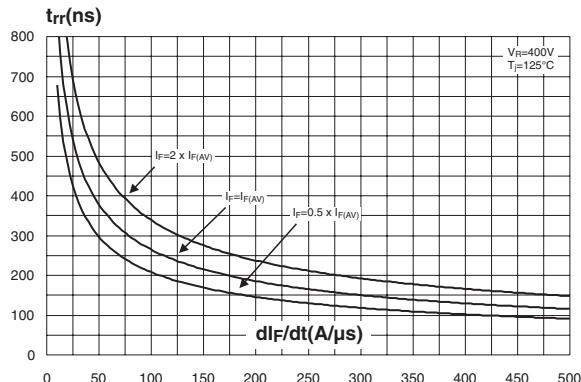


Figure 2: Forward voltage drop versus forward current (per diode)

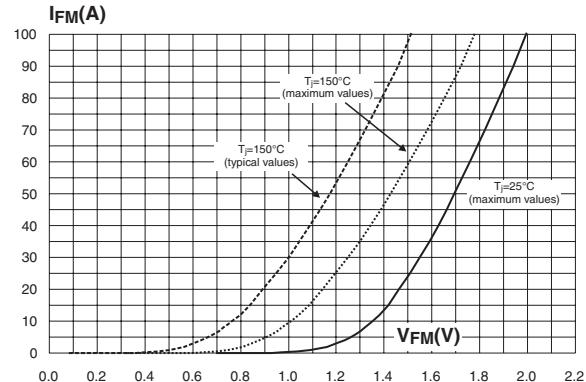


Figure 4: Peak reverse recovery current versus dI_F/dt (typical values, per diode)

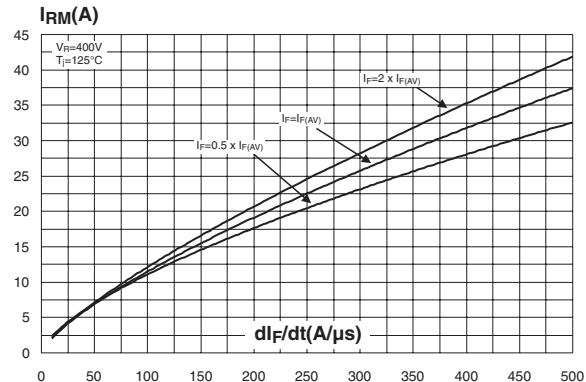


Figure 6: Reverse recovery charges versus dI_F/dt (typical values, per diode)

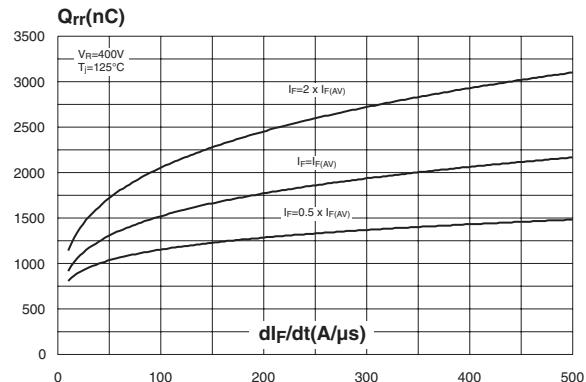




Figure 7: Reverse recovery softness factor versus dI_F/dt (typical values, per diode)

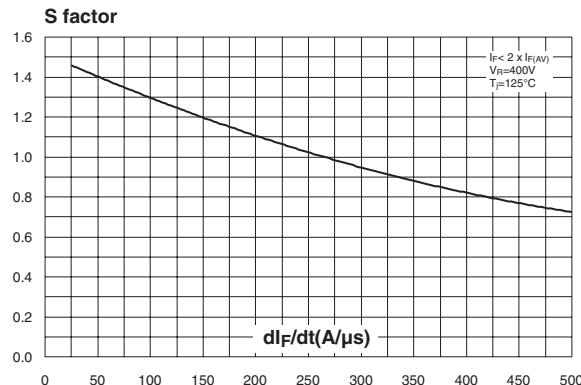


Figure 9: Transient peak forward voltage versus dI_F/dt (typical values, per diode)

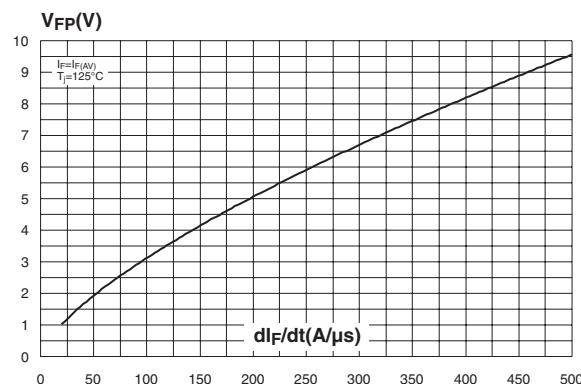


Figure 11: Junction capacitance versus reverse voltage applied (typical values, per diode)

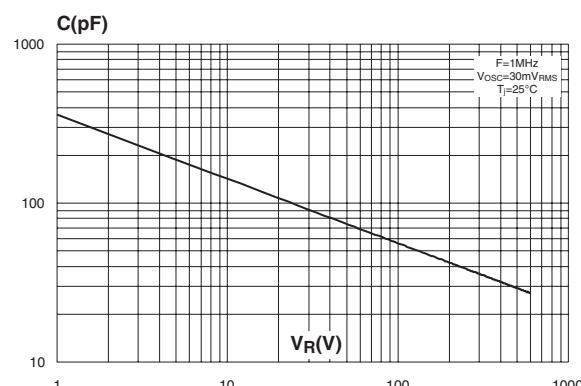


Figure 8: Relative variations of dynamic parameters versus junction temperature

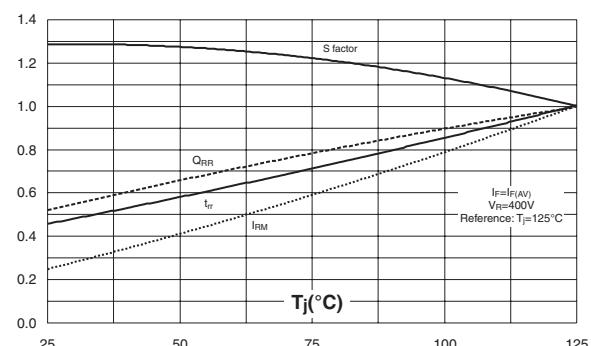
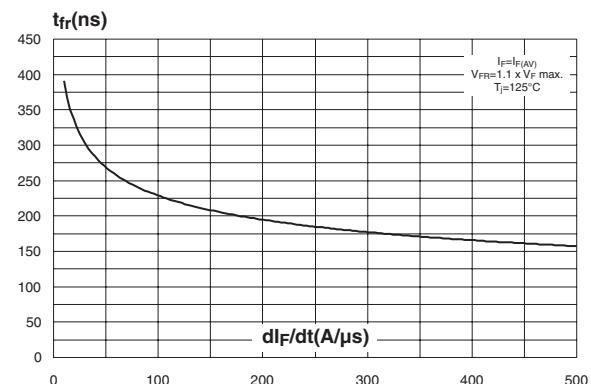
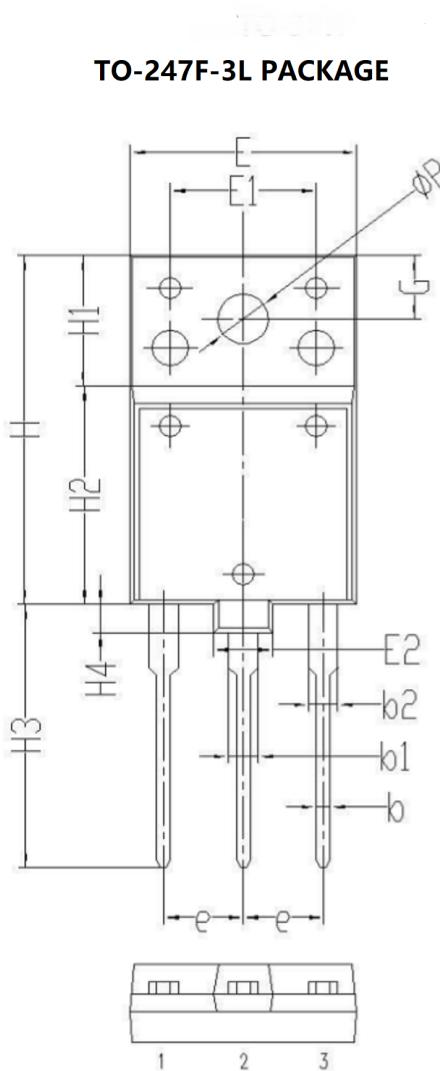


Figure 10: Forward recovery time versus dI_F/dt (typical values, per diode)





Package Information



Symbol	Unit mm		
	Min	Typ	Max
A	5.35	5.55	5.75
A1	2.80	3.00	3.20
A2	1.90	2.10	2.30
A3	1.10	1.30	1.50
b	0.65	0.75	0.85
b1	1.80	2.00	2.20
b2	1.80	2.00	2.20
c	0.70	0.90	1.10
e	5.25	5.45	5.65
E	15.3	15.5	15.7
E1	9.80	10.0	10.2
E2	3.80	4.00	4.20
H	24.3	24.5	24.7
H1	9.00	9.20	9.40
H2	15.1	15.3	15.5
H3	18.5	19.0	19.5
H4	1.80	2.00	2.20
H5	4.80	5.00	5.20
G	4.3	4.5	4.7
ΦP	3.40	3.60	3.80